



SamHop Microelectronics Corp.



STF1016C

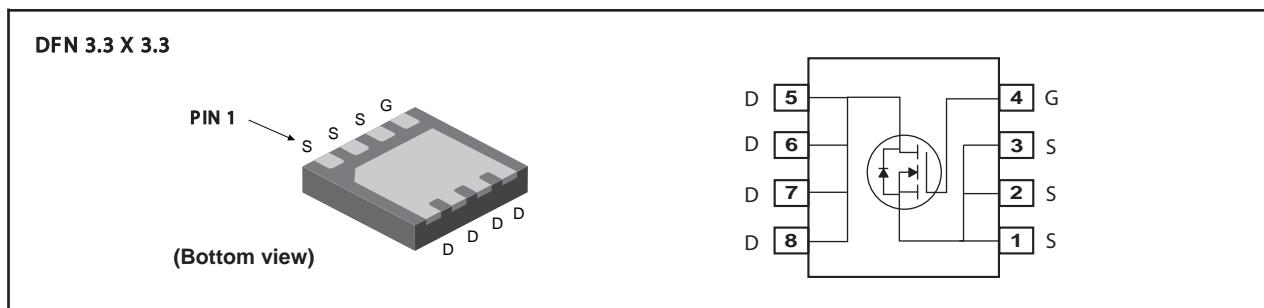
Ver 1.0

N-Channel Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY		
VDSS	ID	RDS(ON) (mΩ) Typ
100V	40A	17 @ VGS=10V
		19 @ VGS=4.5V

FEATURES

- Super high dense cell design for low RDS(ON).
- Rugged and reliable.
- Surface Mount Package.



ABSOLUTE MAXIMUM RATINGS ($T_C=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Limit	Units	
V_{DS}	Drain-Source Voltage ^d	100	V	
V_{GS}	Gate-Source Voltage	± 20	V	
I_D	Drain Current-Continuous ^c	$T_C=25^\circ\text{C}$	40	A
		$T_C=100^\circ\text{C}$	25.3	A
		$T_A=25^\circ\text{C}$	8	A
I_{DM}	-Pulsed ^{a c}	160	A	
E_{AS}	Single Pulse Avalanche Energy ^e	196	mJ	
P_D	Maximum Power Dissipation	$T_C=25^\circ\text{C}$	62.5	W
		$T_A=25^\circ\text{C}$	1.92	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 to 150	$^\circ\text{C}$	

THERMAL CHARACTERISTICS

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	65	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	2	$^\circ\text{C/W}$

Details are subject to change without notice.

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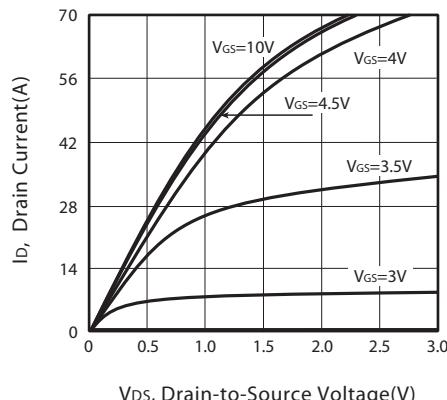
ELECTRICAL CHARACTERISTICS (T_c=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
OFF CHARACTERISTICS						
BV _{DSS}	Drain-Source Breakdown Voltage ^d	V _{GS} =0V , I _D =250uA	100			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =80V , V _{GS} =0V			1	uA
I _{GSS}	Gate-Body Leakage Current	V _{GS} = ±20V , V _{DS} =0V			±100	nA
ON CHARACTERISTICS						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1	2	3	V
R _{D(S(ON))}	Drain-Source On-State Resistance	V _{GS} =10V , I _D =20A		17	19.5	m ohm
		V _{GS} =4.5V , I _D =19A		19	23	m ohm
g _{FS}	Forward Transconductance	V _{DS} =10V , I _D =20A		71		S
DYNAMIC CHARACTERISTICS ^b						
C _{ISS}	Input Capacitance	V _{DS} =25V,V _{GS} =0V f=1.0MHz		2568		pF
C _{OSS}	Output Capacitance			190		pF
C _{RSS}	Reverse Transfer Capacitance			158		pF
SWITCHING CHARACTERISTICS ^b						
t _{D(ON)}	Turn-On Delay Time	V _{DD} =50V I _D =1A V _{GS} =10V R _{GEN} = 6 ohm		48		ns
t _r	Rise Time			53		ns
t _{D(OFF)}	Turn-Off Delay Time			115		ns
t _f	Fall Time			24		ns
Q _g	Total Gate Charge	V _{DS} =50V,I _D =5A,V _{GS} =10V		42		nC
Q _{gs}	Gate-Source Charge	V _{DS} =50V,I _D =5A, V _{GS} =10V		4		nC
Q _{gd}	Gate-Drain Charge			12		nC
DRAIN-SOURCE DIODE CHARACTERISTICS AND MAXIMUM RATINGS						
V _{SD}	Diode Forward Voltage	V _{GS} =0V,I _s =8A		0.77	1.2	V
Notes						
a.Pulse Test:Pulse Width < 10us, Duty Cycle < 1%.						
b.Guaranteed by design, not subject to production testing.						
c.Drain current limited by maximum junction temperature.						
d.Pulse Test:Pulse Width < 1us, Duty Cycle < 1%.						
e.Starting T _J =25°C,L=0.5mH,V _{DD} = 50V.(See Figure13)						
f.Mounted on FR4 Board of 1 inch ² , 2oz.						

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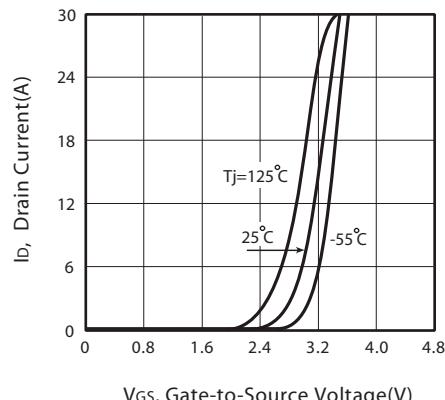
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V_{DS}, Drain-to-Source Voltage(V)

Figure 1. Output Characteristics



V_{GS}, Gate-to-Source Voltage(V)

Figure 2. Transfer Characteristics

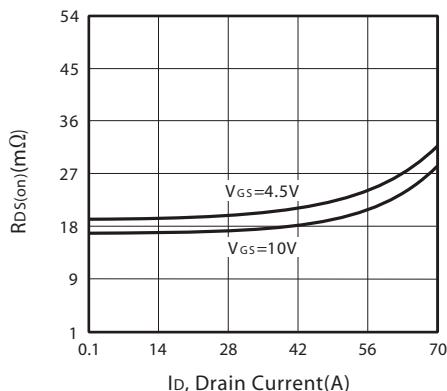


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

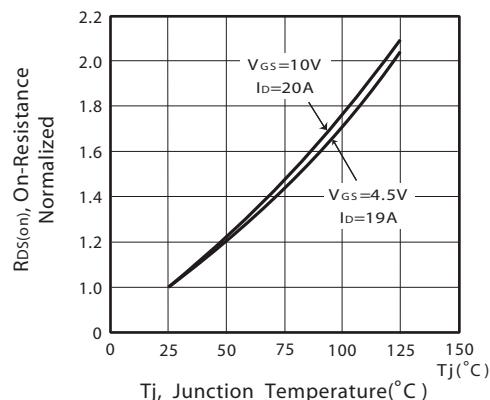


Figure 4. On-Resistance Variation with Drain Current and Temperature

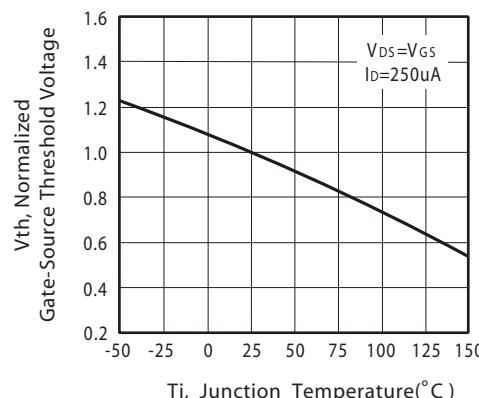


Figure 5. Gate Threshold Variation with Temperature

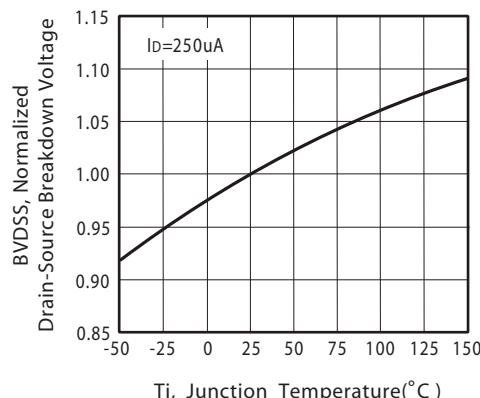
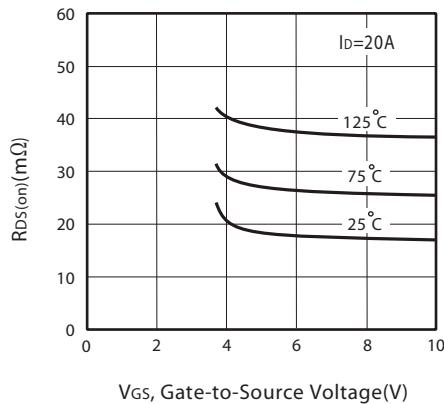


Figure 6. Breakdown Voltage Variation with Temperature

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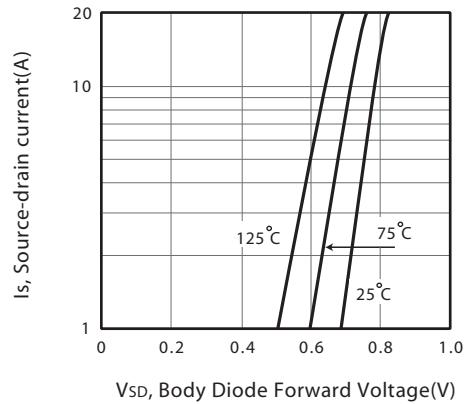
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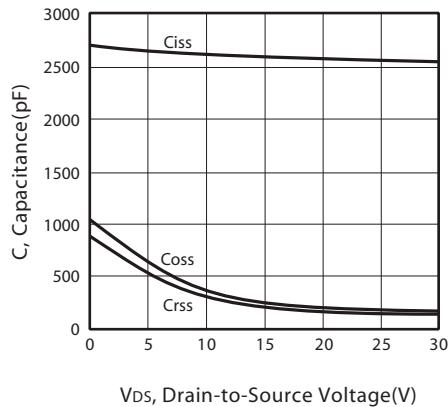
V_{GS}, Gate-to-Source Voltage(V)

Figure 7. On-Resistance vs. Gate-Source Voltage



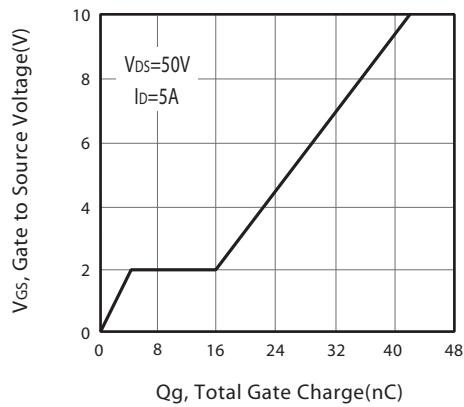
V_{SD}, Body Diode Forward Voltage(V)

Figure 8. Body Diode Forward Voltage Variation with Source Current



V_{DS}, Drain-to-Source Voltage(V)

Figure 9. Capacitance



Q_g, Total Gate Charge(nC)

Figure 10. Gate Charge

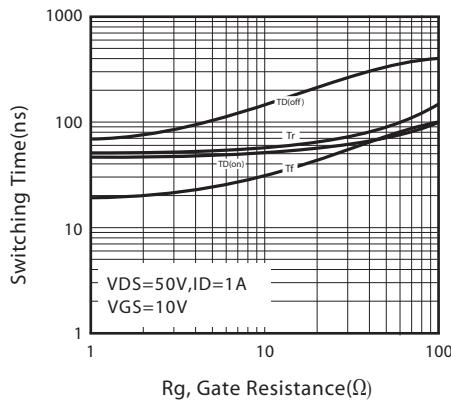


Figure 11. switching characteristics

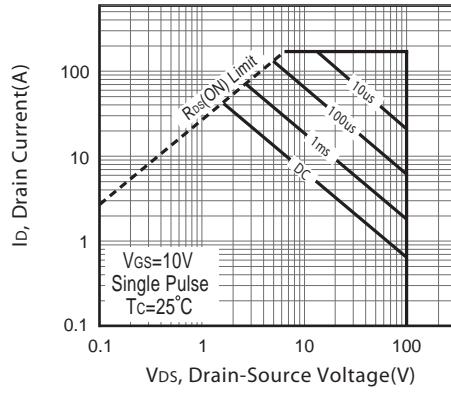
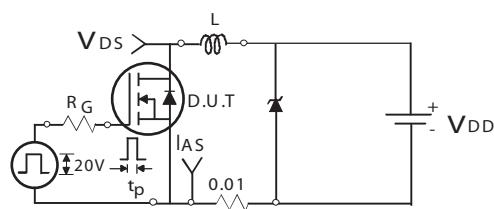


Figure 12. Maximum Safe Operating Area

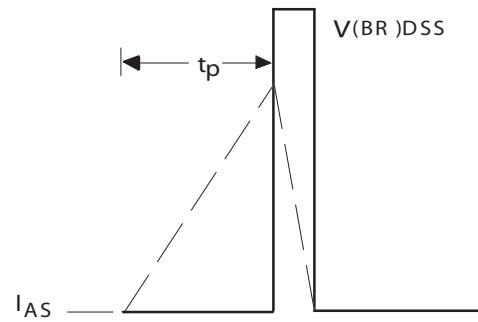
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Unclamped Inductive Test Circuit

Figure 13a.



Unclamped Inductive Waveforms

Figure 13b.

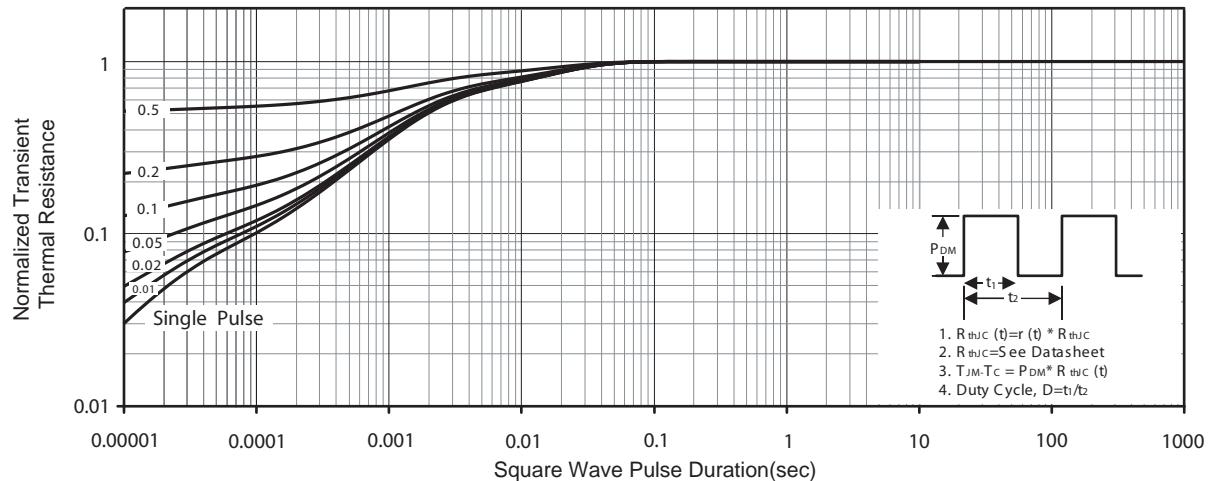
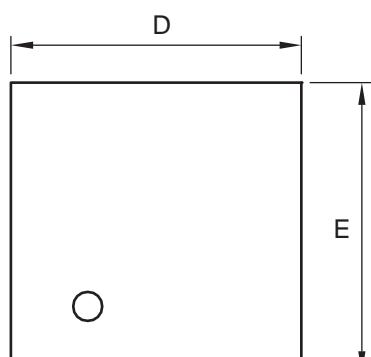


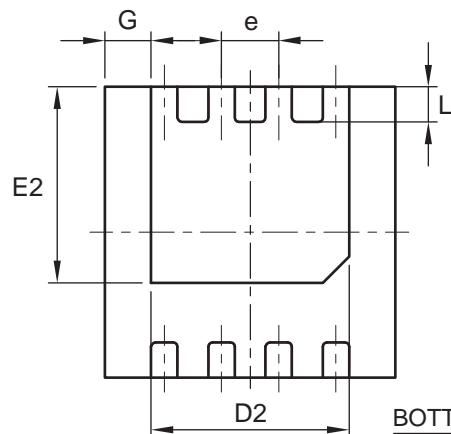
Figure 14. Normalized Thermal Transient Impedance Curve

PACKAGE OUTLINE DIMENSIONS

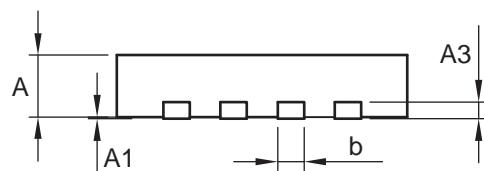
DFN 3.3 x 3.3



TOP VIEW



BOTTOM VIEW

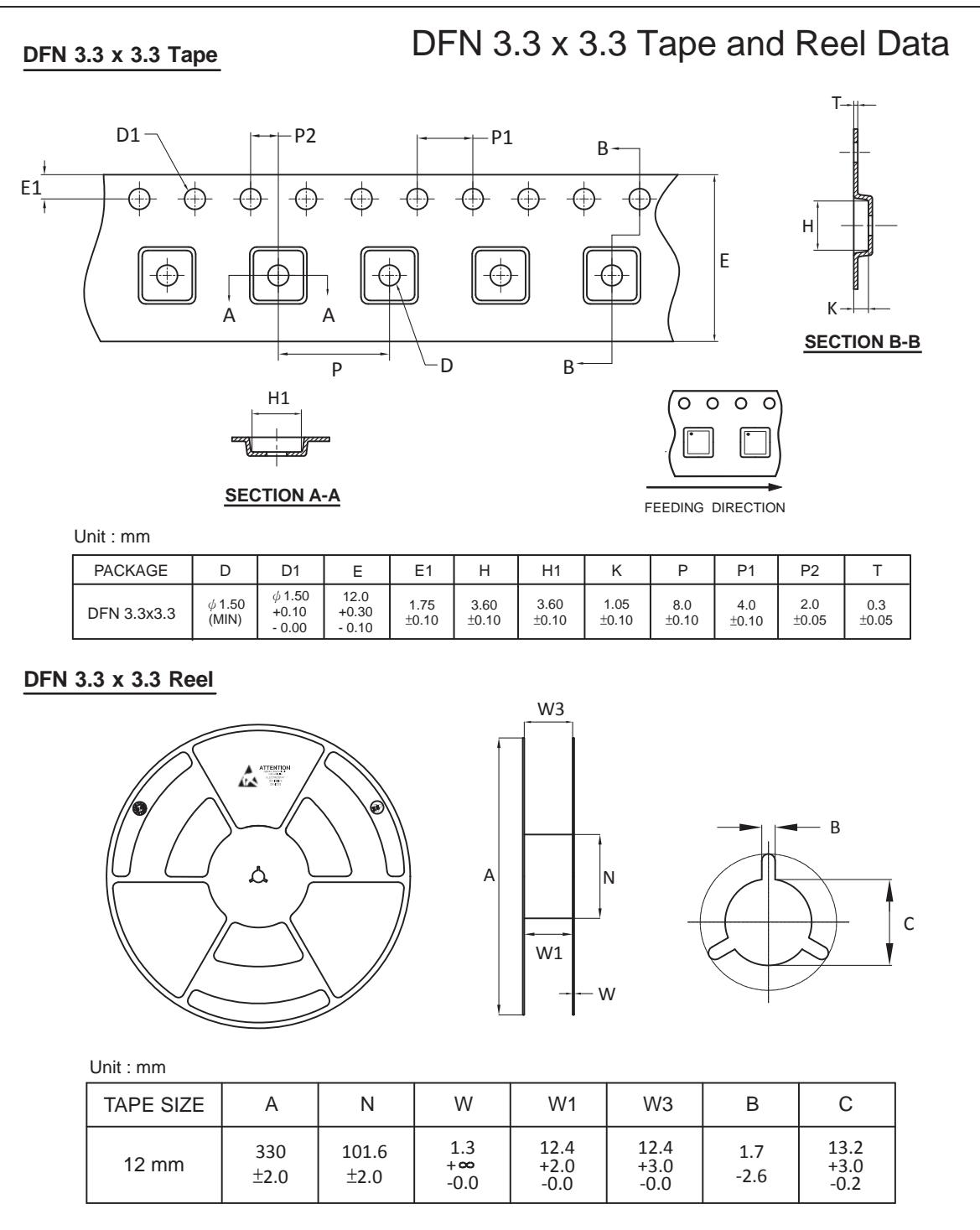


SIDE VIEW

SYMBOLS	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.70	0.75	0.80
A1	—	—	0.05
A3	0.10	0.15	0.25
b	0.24	0.30	0.35
D	3.15	3.30	3.40
D2	2.10	2.25	2.35
E	3.15	3.30	3.40
E2	2.15	2.25	2.35
e	0.60	0.65	0.70
G	0.475	0.525	0.575
L	0.35	0.40	0.45

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TOP MARKING DEFINITION

DFN 3.3 x 3.3

